

**Product / Package Information**

Package	TSOT - COL
Body Size/Pitch	
LeadCount	5
Option	NiPdAu

**Environmental Compliance Information**

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

**Materials Declaration**

**Molding Compound**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	5.20 E-03	87.3	873000	44.93	449317
Thermosets	Phenol Resin	Proprietary	2.68 E-04	4.5	45000	2.32	23161
Thermosets	Epoxy Resin 1	Proprietary	1.79 E-04	3.0	30000	1.54	15440
Thermosets	Epoxy Resin 2	Proprietary	1.79 E-04	3.0	30000	1.54	15440
Others	Others	Proprietary	1.19 E-04	2.0	20000	1.03	10294
Other inorganic materials	Carbon Black	1333-86-4	1.19 E-05	0.2	2000	0.10	1029
Subtotal			5.96 E-03	100.0	1000000	51	514681

**Leadframe**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	4.43 E-03	97.5	975000	38.24	382407
Copper & its alloys	Iron	7439-89-6	1.07 E-04	2.35	23500	0.92	9217
Copper & its alloys	Zinc	7440-66-6	5.45 E-06	0.12	1200	0.05	471
Copper & its alloys	Phosphorus	7723-14-0	1.36 E-06	0.03	300	0.01	118
Subtotal			4.54 E-03	100	1000000	39	392212

**Internal/External Leadframe Plating**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Nickel & its alloys	Nickel	7440-02-0	5.29 E-05	90.91	909091	0.46	4568
Precious metals	Palladium	7440-05-3	4.60 E-06	7.91	79051	0.04	397
Precious metals	Gold	7440-57-5	6.90 E-07	1.19	11858	0.01	60
Subtotal			5.82 E-05	100.00	1000000	0.50	5025

**Bond Wires**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	1.50 E-04	99.99	1000000	1.30	12952

**Chip**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	8.00 E-04	100	1000000	6.91	69085

**Die Attach**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Aluminum oxide	1344-28-1	2.45 E-05	35	350000	0.21	2116
Other organic materials	Diethylene glycol monoethyl ether acetate	112-15-1	2.45 E-05	35	350000	0.21	2116
Thermoset	Epoxy Resin	Proprietary	1.75 E-05	25	250000	0.15	1511
Others	Amine	Proprietary	3.50 E-06	5	50000	0.03	302
Subtotal			7.00 E-05	100	1000000	0.60	6045

<b>Package Totals</b>			<b>Weight (g)</b> 1.16 E-02			<b>Percentage (%)</b> 100	<b>PPM</b> 1000000
-----------------------	--	--	--------------------------------	--	--	------------------------------	-----------------------

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability any inaccuracy of such information.



ADI Proprietary

Product / Package Information	
Package	TSOT
Body Size/Pitch	
Lead Count	5
Terminal Finish	100 Sn

Environmental Compliance Information	
RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
JIG Material Content Compliant	Level A & B Compliant
REACH SVHC Compliant	Yes

### Materials Declaration

#### Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	5.20 E-03	87.3	873000	42.76	427646
Thermosets	Phenol Resin	Proprietary	2.68 E-04	4.5	45000	2.20	22044
Thermosets	Epoxy Resin 1	Proprietary	1.79 E-04	3.0	30000	1.47	14696
Thermosets	Epoxy Resin 2	Proprietary	1.79 E-04	3.0	30000	1.47	14696
Others	Others	Proprietary	1.19 E-04	2.0	20000	0.98	9797
Other inorganic materials	Carbon Black	1333-86-4	1.19 E-05	0.2	2000	0.10	980
Subtotal			5.96 E-03	100.0	1000000	49	489858

#### Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	4.44 E-03	97.5	975000	36.49	364940
Copper & its alloys	Iron	7439-89-6	1.07 E-04	2.35	23500	0.88	8796
Copper & its alloys	Zinc	7440-66-6	5.46 E-06	0.12	1200	0.04	449
Copper & its alloys	Phosphorus	7723-14-0	1.37 E-06	0.03	300	0.01	112
Subtotal			4.55 E-03	100	1000000	37	374297

#### Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	4.60 E-05	100	1000000	0.38	3781

#### External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	5.87 E-04	100	1000000	4.82	48231

#### Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	1.50 E-04	99.99	1000000	1.23	12327

#### Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	8.00 E-04	100	1000000	6.58	65753

#### Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	5.64 E-05	80.50	805000	0.46	4631
Other organic materials	Carbocyclic Acrylates	Proprietary	7.00 E-06	10.00	100000	0.06	575
Other organic materials	Bismaleimide resin	Proprietary	2.10 E-06	3.00	30000	0.02	173
Other organic materials	2-preponic acid, 2-methyl	68586-19-6	2.10 E-06	3.00	30000	0.02	173
Others	Additive	Proprietary	2.10 E-06	3.00	30000	0.02	173
Other organic materials	Dicumyl peroxide	80-43-3	3.50 E-07	0.5	5000	0.00	29
Subtotal			7.00 E-05	100.00	1000000	0.58	5753

Package Totals			Weight (g)	Percentage (%)	PPM
			1.22 E-02	100	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability any inaccuracy of such information.



ADI Proprietary